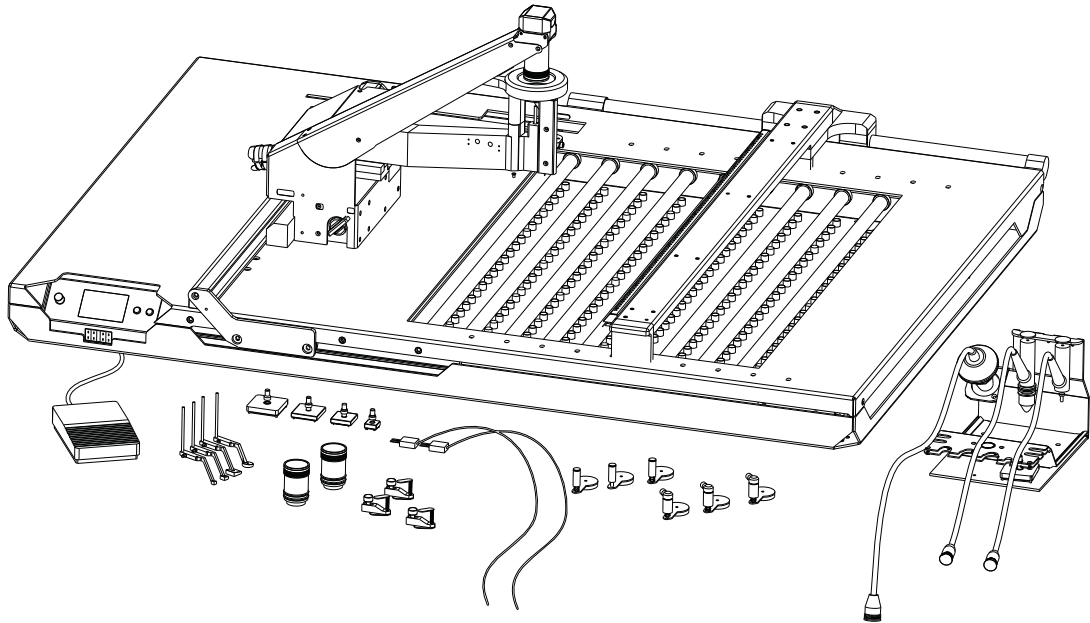


EXPERT 10.6-HXXV


Rework Station with 10000W hybrid under heater. The heating area of 500x650mm² is adjustable to PCB size. Automated SMD placement process by Auto-Vision-Placer (AVP) incl. Easy-Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for large size PCBs like server boards, telecommunication or batch PCBs with mid-size to very big components.

Standard Equipment (Art.No DB00.1071)





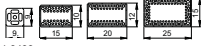



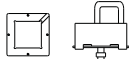



- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5mm, 8mm, 15mm with O-Ring
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (Type K)
- Six PCB magnet holders 40.5mm (3xstandard and 3xEasy-Lock)
- Three PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

Technical Data

| | | |
|------------------------------|---------------------------------------------------------------------|-------------|
| System power consumption: | 10500 VA | |
| Power solder pen: | 300 W, 35 l/min | |
| Power underheater: | 5000 - 10000 W, 9 x IR-lamps | |
| Effective heating area: | 500 x 650 mm ² | |
| PCB size recommended: | 530 x 710 mm ² | |
| Resolution motion system: | 0.001 mm | |
| Placement accuracy | ± 0.030 mm | (CSP) |
| | ± 0.040 mm | (BGA) |
| | ± 0.070 mm | (Maxi BGA)* |
| High resolution CMOS-camera: | 5 Mio. Pixel, USB2 | |
| Camera field of view (FOV): | 32 x 42 mm ² | (CSP) |
| | 42 x 57 mm ² | (BGA) |
| | 71 x 96 mm ² | (Maxi BGA)* |
| Mains: | 3 Phases, 400VAC, Fuse 16A, Type C Connector Type CEE 32A (3 phase) | |
| Pressurized air: | 5 - 8 bar, 100 l/min Clean dry air | |
| Foot print: | 13000 x 900 mm ² | |
| *Optional extras | | |

EXPERT 10.6-HXXV

Optional Extras

| | | |
|-----------|------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------|
| DVSX.0007 | Report with pcb identification for ES 05, licence RP |  Report |
| SF66.0110 | Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm |  Maxi-BGA AVP4 |
| LW40.1097 | Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16) |  (length + 1.4 mm) |
| LW40.1099 | Solder nozzle set BGA 7^ for all (98%) types of BGA, 7 pieces |  |
| LW01.0400 | Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces |  (length + 1.4 mm) |
| LW01.0100 | Soldering tool set QFP for all PLCC ..QFP, 7 pieces |  |
| SF36.1005 | PCB flex support 40.5 HIF 10, "18 pin" |  |
| SF03.0014 | PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF/HIF |  40.5 |
| LWxx.xxx4 | Reballing oven and mask for all types of BGA/CSP, your choice |  |
| SF71.0001 | Side Camera for ES 05, camera, stand, cable, DVD |  |
| DB00.0025 | Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum |  N |
| SF00.0028 | Line connector CEE 32 A for HIF-08/09/10/IRF07 with hints |  |